# **MOSFET** - N-Channel Shielded Gate PowerTrench<sup>®</sup>

## 150 V, 5.0 mΩ, 139 A

# NTP5D0N15MC

#### Features

- Shielded Gate MOSFET Technology
- Max  $R_{DS(on)} = 5.0 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 97 \text{ A}$
- 50% Lower Qrr than other MOSFET Suppliers
- Lowers Switching Noise/EMI
- 100% UIL Tested
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Typical Applications**

- Synchronous Rectification for ATX / Server / Telecom PSU
- Motor Drives and Uninterruptible Power Supplies
- Micro Solar Inverter

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parar	Symbol	Value	Unit		
Drain-to-Source Voltage			V <sub>DSS</sub>	150	V
Gate-to-Source Voltage	Gate-to-Source Voltage				V
$\begin{array}{l} \text{Continuous Drain} \\ \text{Current } R_{\theta JC} \\ \text{(Note 2)} \end{array}$	Steady $T_{\rm C} = 25^{\circ}{\rm C}$		۱ <sub>D</sub>	139	A
Power Dissipation $R_{\theta JC}$ (Note 2)	State	-	P <sub>D</sub>	214	W
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2)	Steady State	T <sub>A</sub> = 25°C	Ι <sub>D</sub>	15	A
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)	Glaie		P <sub>D</sub>	2.4	W
Pulsed Drain Current	$T_A = 25^\circ$	C, t <sub>p</sub> = 100 μs	I <sub>DM</sub>	818	А
Operating Junction and Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +175	°C		
Single Pulse Drain-to-S Energy (I <sub>L</sub> = 26 A <sub>pk</sub> , L =	E <sub>AS</sub>	1014	mJ		
Lead Temperature for S (1/8" from case for 10 s)	ΤL	260	°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface-mounted on FR4 board using a 1 in<sup>2</sup>, 2 oz. Cu pad.

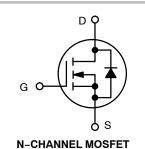
The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

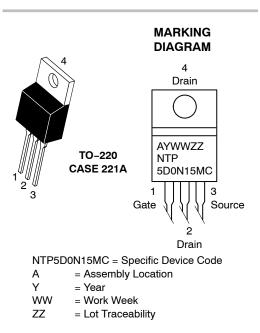


#### **ON Semiconductor®**

#### www.onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
150 V	5.0 m $\Omega$ @ 10 V	139 A





#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTP5D0N15MC	TO-220 (Pb-Free)	800 / Tube

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 2)	$R_{ ext{ heta}JC}$	0.7	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{ hetaJA}$	62.5	

#### **ELECTRICAL CHARACTERISTICS** (T<sub>1</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condi	tion	Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		150			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> / T <sub>J</sub>	$I_D = 250 \ \mu A$ , ref to $25^{\circ}C$			76		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$ , $T_{J} = 25^{\circ}C$ $V_{DS} = 120 V$				1.0	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$	= ±20 V			±100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> =	= 532 μA	2.5		4.5	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>	I <sub>D</sub> = 532 μA, ref	to 25°C		-8.5		mV/°0
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 97 A			4.2	5	mΩ
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 97 A			146		S
CHARGES, CAPACITANCES & GATE RESIS	TANCE						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 75 V			6300		pF
Output Capacitance	C <sub>OSS</sub>				1900		
Reverse Transfer Capacitance	C <sub>RSS</sub>				13		
Gate-Resistance	R <sub>G</sub>				1.1	2.2	Ω
Total Gate Charge	Q <sub>G(TOT)</sub>				75		
Threshold Gate Charge	Q <sub>G(TH)</sub>				18		nC
Gate-to-Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 7	5 V; I <sub>D</sub> = 97 A		31		
Gate-to-Drain Charge	Q <sub>GD</sub>				10		1
Plateau Voltage	V <sub>GP</sub>	1			5.4		V
Output Charge	Q <sub>OSS</sub>	V <sub>DD</sub> = 75 V, V <sub>GS</sub> = 0 V			227		nC
SWITCHING CHARACTERISTICS (Note 3)							
Turn-On Delay Time	t <sub>d(ON)</sub>				32		
Rise Time	t <sub>r</sub>	$V_{GS}$ = 10 V, $V_{DD}$ = 75 V, $I_{D}$ = 97 A, $R_{G}$ = 4.7 $\Omega$			14		
Turn-Off Delay Time	t <sub>d(OFF)</sub>				45		ns

#### DRAIN-SOURCE DIODE CHARACTERISTICS

Fall Time

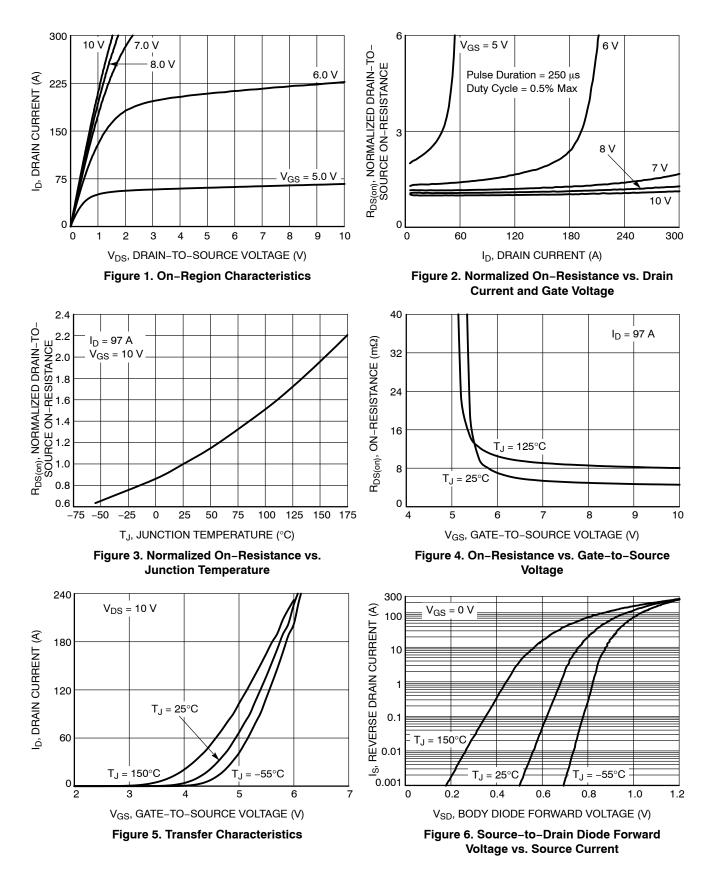
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 97 A	T <sub>J</sub> = 25°C	0.96	1.2	V
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, V <sub>DD</sub> = 75 V		92		ns
Reverse Recovery Charge	Q <sub>RR</sub>	dI <sub>S</sub> /dt = 100 A/µs,	189		nC	

9.0

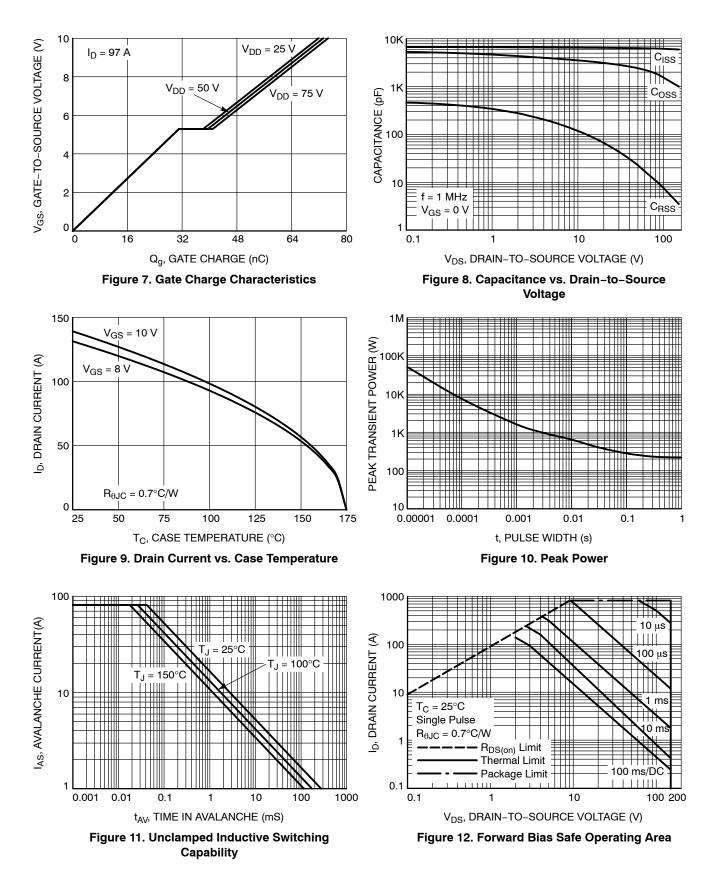
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Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**



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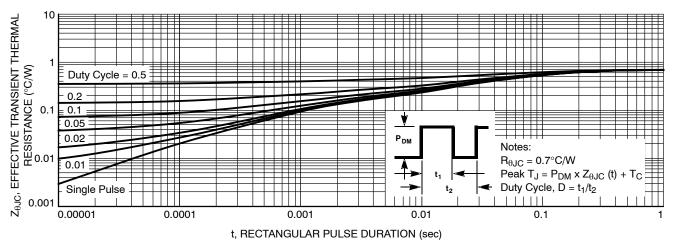


Figure 13. Transient Thermal Impedance

S

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		TO-220 CASE 221A ISSUE AK						DATE	13 JAN 2022
SCALE 1:1			1. C 2. C 3. C	CONTR DIMEN LEAD	ROLLING DI ISION Z DEI D IRREGULA	MENSION FINES A ZO ARITIES AR	ONE WHERE AL E ALLOWED.		
			4. N	лах м	VIDTHFOR	F102 DEV	ICE = 1.35MM		
			Г		INC	HES	MILLIM	ETERS	
				ым 🛛	MIN.	MAX.	MIN.	MAX.	
	2 3			A	0.570	0.620	14.48	15.75	
				в	0.380	0.415	9.66	10.53	
н —	₩₩			с	0.160	0.190	4.07	4.83	
	7 \7	H I		D	0.025	0.038	0.64	0.96	
z_				F	0.142	0.161	3.60	4.09	
<u> </u>	I K			G	0.095	0.105	2.42	2.66	
				н	0.110	0.161	2.80	4.10	
	Щ Щ <u> </u>	Ü I		J	0.014	0.024	0.36	0.61	
	Г <mark>і</mark>			к	0.500	0.562	12.70	14.27	
V — + I I-	►- <b>  </b> ``.			L	0.045	0.060	1.15	1.52	
G <del></del>	.  <mark> </mark> <sup></sup> J <sup>−</sup>			N	0.190	0.210	4.83	5.33	
· · · ·	- <b>→  </b> D			Q	0.100	0.120	2.54	3.04	
	N 🖛			R	0.080	0.110	2.04	2.79	
				s	0.045	0.055	1.15	1.41	
				т	0.235	0.255	5.97	6.47	
				U	0.000	0.050	0.00	1.27	
				V	0.045		1.15		
				Z		0.080		2.04	
2. 3. 4. STYLE 5: PIN 1. 2.	BASE         PIN 1.           COLLECTOR         2.           EMITTER         3.           COLLECTOR         4.           STYLE 6:         GATE           DRAIN         2.	EMITTER COLLECTOR EMITTER ANODE CATHODE	IN 1. CAT 2. ANO 3. GAT 4. ANO LE 7: IN 1. CAT 2. ANO	ode Te ode Thode ode		2. 3. 4. STYLE 8: PIN 1. 2.	MAIN TERMINAL MAIN TERMINAL GATE MAIN TERMINAL CATHODE ANODE	2	
4. STYLE 9: PIN 1.	DRAIN 4. STYLE 10 GATE PIN 1.	ANODE CATHODE GATE P SOURCE	3. CAT 4. ANO LE 11: IN 1. DR/ 2. SOU	ode Ain		4. STYLE 12: PIN 1.	EXTERNAL TRIP ANODE MAIN TERMINAL MAIN TERMINAL	. 1	
3.	EMITTER 3.	DRAIN SOURCE	3. GAT 4. SOL	ΤE		3.	GATE NOT CONNECTI		

 
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